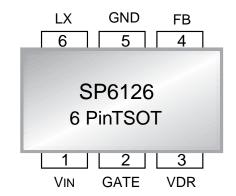


# High-Voltage, Step Down Controller in TSOT6

#### **FEATURES**

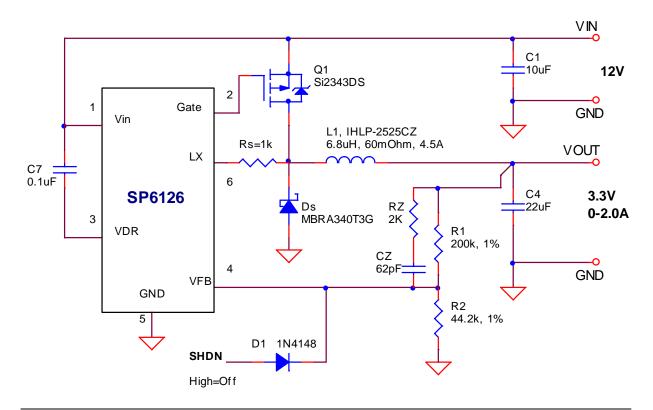
- Wide 4.5V 29V Input Voltage Range
- Internal Compensation
- Built-in High Current PMOS Driver
- Adjustable Overcurrent Protection
- Internal soft-start
- 600kHz Constant Frequency Operation
- 0.6V Reference Voltage
- 1% output setpoint accuracy
- Lead Free, RoHS Compliant Package: Small 6-Pin TSOT



**DESCRIPTION** 

The SP6126 is a PWM controlled step down (buck) voltage mode regulator with VIN feedforward and internal Type-II compensation. It operates from 4.5V to 29V making is suitable for 5V, 12V, and 24V applications. By using a PMOS driver, this device is capable of operating at 100% duty cycle. The high side driver is designed to drive the gate 5V below VIN. The programmable overcurrent protection is based on high-side MOSFET's ON resistance sensing and allows setting the overcurrent protection value up to 300mV threshold (measured from VIN-LX). The SP6126 is available in a space-saving 6-pin TSOT package making it the smallest controller available capable of operating from 24VDC supplies.

TYPICAL APPLICATION CIRCUIT





#### **ABSOLUTE MAXIMUM RATINGS**

These are stress ratings only, and functional operation of the device at these ratings or any other above those indicated in the operation sections of the specifications below is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability.

Input Voltage	0.3V to 30V
Lx	2V to 30V
FB	0.3V to 5.5V
Storage Temperature	65 °C to 150 °C
Junction Temperature	40°C to 125°C
Lead Temperature (Soldering, 10 sec)	300 °C
ESD Rating1kV LX, 2kV all of	

#### • ELECTRICAL SPECIFICATIONS

Specifications are for  $T_{AMB}=T_{J}=25^{\circ}C$ , and those denoted by  $\bullet$  apply over the full operating range, -40°C<  $T_{j}$  <125°C. Unless otherwise specified:  $V_{IN}=4.5V$  to 29V,  $C_{IN}=4.7\mu F$ .

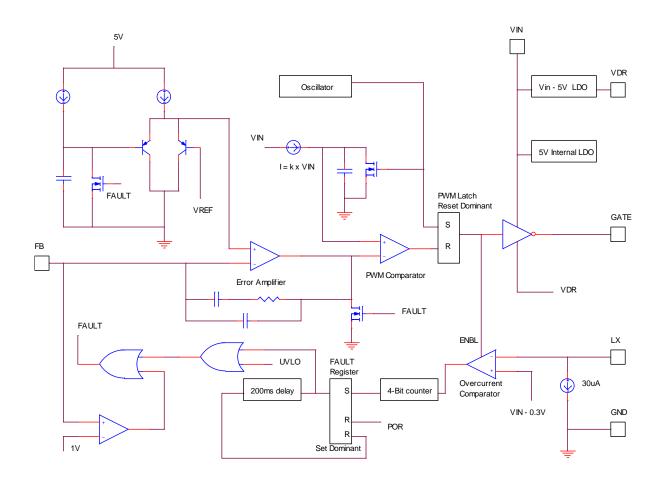
PARAMETER	MIN	TYP	MAX	UNITS	<b>♦</b>	CONDITIONS
UVLO Turn-On Threshold	4.2	4.35	4.5	V		0°C< T <sub>j</sub> <125°C
UVLO Turn-Off Threshold	4.0	4.2	4.4	V		0°C< T <sub>j</sub> <125°C
UVLO Hysterisis		0.2		V		
Operating Input Voltage Range	4.5		29	V		0°C< T <sub>j</sub> <125°C
Operating Input Voltage Range	7		29	V	<b>♦</b>	
Operating VCC Current		0.3	3	mA		VFB=1.2V
Reference Voltage Accuracy		0.5		%		
Reference Voltage Accuracy		0.5	2	%	<b>♦</b>	
Reference Voltage		0.6		V		
Reference Voltage	0.588	0.6	0.612	V	<b>♦</b>	
Switching Frequency	510	600	690	kHz		
Peak-to-peak ramp Modulator		VIN/5		V		
Minimum ON-Time Duration		40	100	ns	<b>♦</b>	
Minimum Duty Cycle			0	%		
Maximum Duty Cycle	100			%		
Gate Driver Turn-Off Resistance		50	60	kΩ		Internal resistor between GATE and VIN
Gate Driver Pull-Down Resistance		4	8	Ω		VIN=12V, V <sub>FB</sub> =0.5V, Measure resistance between GATE and VDR
Gate Driver Pull-up Resistance		3	6	Ω		VIN=12V, V <sub>FB</sub> =0.7V, Measure resistance between GATE and VIN
VIN - VDR voltage difference	4.5		5.5	V	<b>♦</b>	Measure VIN - VDR, VIN>7V
Overcurrent Threshold	270	300	330	mV		Measure VIN - LX
LX pin Input Current	25	30	35	uA		$V_{LX} = VIN$
OFF interval during hiccup		100		ms		
Soft start time	3	5	9	ms		VFB=0.58V, measure between VIN=4.5V and first GATE pulse
SHDN Threshold	0.9	1.0	1.1	V	<b>♦</b>	Apply voltage to FB
SHDN Threshold Hysteresis		100		mV		





PIN#	PIN NAME	DESCRIPTION
1	VIN	Input power supply for the controller. Place input decoupling capacitor as close as possible to this pin.
2	GATE	Connect to the gate terminal of the external P-channel MOSFET.
3	VDR	Power supply for the internal driver. This voltage is internally regulated to about 5V below VIN. Place a 0.1uF decoupling capacitor between VDR and VIN as close as possible to the IC.
4	FB	Regulator feedback input. Connect to a resistive voltage-divider network to set the output voltage. This pin can be also used for ON/OFF control. If this pin is pulled above 1V the P-channel driver is disabled and controller resets internal soft start circuit.
5	GND	Ground pin.
6	LX	This pin is used as a current limit input for the internal current limit comparator. Connect to the drain pin of the external MOSFET through an optional resistor. Internal threshold is pre-set to $300\text{mV}$ nominal and can be decreased by changing the external resistor based on the following formula: $V_{\text{TRSHLD}} = 300\text{mV} - 30\text{uA} * \text{R}$

#### BLOCK DIAGRAM





The SP6126 is a fixed frequency, voltagemode, non-synchronous PWM controller optimized for minimum component, small form factor and cost effectiveness. It has been designed for single-supply operation ranging from 4.5V to 29V. SP6126 has Type-II internal compensation for use Electrolytic/Tantalum output capacitors. For ceramic capacitors Type-III compensation can be implemented by simply adding an R and C between output and Feedback. A precision 0.6V reference, present on the positive terminal of the Error Amplifier, permits programming of the output voltage down to 0.6V via the FB pin. The output of the Error Amplifier is internally compared to a feed-forward (VIN/5 peak-topeak) ramp and generates the PWM control. Timing is governed by an internal oscillator that sets the PWM frequency at 600kHz.

SP6126 contains useful protection features. Over-current protection is based on high-side MOSFET's Rds(on) and is programmable via a resistor placed at LX node. Under-Voltage Lock-Out (UVLO) ensures that the controller starts functioning only when sufficient voltage exists for powering IC's internal circuitry.

#### **SP6126 Loop Compensation**

SP6126 includes The Type-II internal compensation components for dool compensation. External compensation components are not required for systems with tantalum or aluminum electrolytic output capacitors with sufficiently high ESR. Use the condition below as a guideline to determine whether or not the internal compensation is sufficient for your design.

Type-II internal compensation is sufficient if the following condition is met:

$$f_{\it ESRZERO} < f_{\it DBPOLE}$$
 .....(1)

where:

$$f_{ESRZERO} = \frac{1}{2.\pi . R_{ESR} . C_{OUT}}$$
 .....(2)

$$f_{DBPOLE} = \frac{1}{2.\pi.\sqrt{L \cdot C_{OUT}}}$$
 .....(3)

#### **Creating a Type-III compensation Network**

The above condition requires the ESR zero to be at a lower frequency than the double-pole from the LC filter. If this condition is not met, Type-III compensation should be used and can be accomplished by placing a series RC combination in parallel with R1 as shown below. The value of CZ can be calculated as follows and RZ selected from table 1.

$$CZ = \frac{\sqrt{L \cdot C}}{R1} \dots (4)$$

$f_{\text{ESRZERO}} \div f_{\text{DBPOLE}}$	RZ
1X	50ΚΩ
2X	40ΚΩ
3X	30ΚΩ
5X	10ΚΩ
>= 10X	2ΚΩ

Table1- Selection of RZ

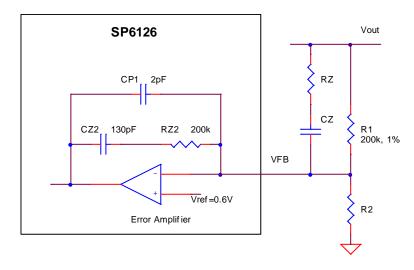


Figure 1- RZ and CZ in conjunction with internal compensation components form a Type-III compensation



Loop Compensation Example 1- A converter utilizing a SP6126 has a 6.8uH inductor and a 22uF/5m $\Omega$  ceramic capacitor. Determine whether Type-III compensation is needed.

From equation (2)  $f_{ESRZERO} = 1.45 MHz$ . From equation (3)  $f_{DBPOLE} = 13$  kHz. Since the condition specified in (1) is not met, Type-III compensation has to be used by adding external components RZ and CZ. Using equation (4) CZ is calculated 61.2pF (use 62 pF). Following the guideline given in table 1, a  $2k\Omega$  RZ should be used.

The steps followed in example 1 were used to compensate the typical application circuit shown on page 1. Satisfactory frequency response of the circuit, seen in figure 2, validates the above procedure.

Loop Compensation Example 2- A converter utilizing a SP6126 has a 6.8uH inductor and a 150uF,  $82m\Omega$  Aluminum Electrolytic capacitor. Determine whether Type-III compensation is needed.

From equation (2)  $f_{\rm ESRZERO} = 13 \rm kHz$ . From equation (3)  $f_{\rm DBPOLE} = 5 \rm \ kHz$ . Since the condition specified in (1) is not met, Type-III compensation has to be used by adding external components RZ and CZ. Using equation (4) CZ is calculated 160pF (use 150 pF). Since  $f_{\rm ESRZERO} \div f_{\rm DBPOLE}$  is approximately 3, RZ has to be set at  $30 \rm k\Omega$ .

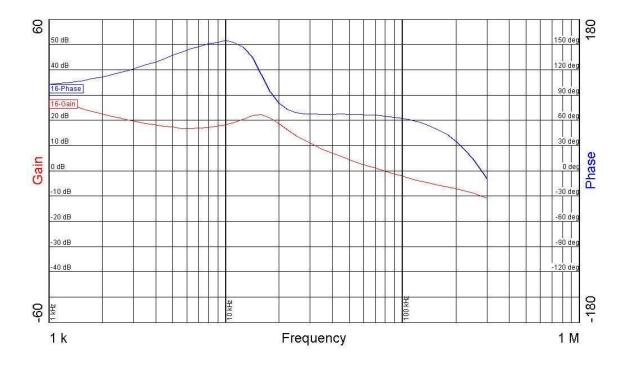


Figure 2- Satisfactory frequency response of typical application circuit shown on page 1. Crossover frequency fc is 80kHz with a corresponding phase margin of 65 degrees.

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#### **Overcurrent Protection**

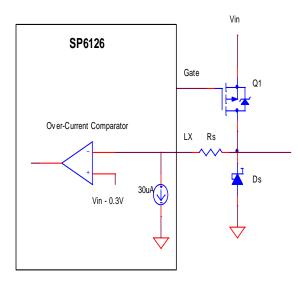


Figure 3- Overcurrent protection circuit

The overcurrent protection circuit functions by monitoring the voltage across the high-side FET Q1. When this voltage exceeds 0.3V, the overcurrent comparator triggers and the controller enters hiccup mode. For example if Q1 has Rds(on)=0.1 $\Omega$ , then the overcurrent will trigger at I = 0.3V/0.1 $\Omega$ =3A. To program a lower overcurrent use a resistor Rs as shown in figure 1. Calculate Rs from:

$$Rs = \frac{0.3 - (1.15 \times Iout \times Rds(on))}{30uA} \dots (5)$$

The overcurrent circuit triggers at peak current through Q1 which is usually about 15% higher than average output current. Hence the multiplier 1.15 is used in (5).

Example: A switching MOSFET used with SP6126 has Rds(on) of  $0.1\Omega$ . Program the over-current circuit so that maximum output is 2A.

$$Rs = \frac{0.3 - (1.15 \times 1A \times 0.1Ohm)}{30uA}$$

$$Rs = 2333\Omega$$

Using the above equation there is good agreement between calculated and test results when an RS in the range of 0.5k to 3k is used. For RS larger than 3k test results are lower than those predicted by (5), due to circuit parasitics.

#### **Using the ON/OFF Function**

Feedback pin serves a dual role of ON/OFF control. The MOSFET driver is disabled when a voltage greater than 1V is applied at FB pin. Maximum voltage rating of this pin is 5.5V. The controlling signal should be applied through a small signal diode as shown on page 1. Please note that an optional  $10k\Omega$  bleeding resistor across the output helps keep the output capacitor discharged under no load condition.

#### **Programming the Output Voltage**

To program the output voltage, calculate R2 using the following equation:

$$R2 = \frac{R1}{\left(\frac{Vout}{Vref} - 1\right)}$$

Where: Vref=0.6 is the reference voltage of the SP6126

R1=200k $\Omega$  is a fixed-value resistor that, in addition to being a voltage divider, it is part of the compensation network. In order to simplify compensation calculations, R1 is fixed at 200k $\Omega$ .

#### **Soft Start**

Soft Start is preset internally to 5ms (nominal). Internal Soft Start eliminates the need for the external capacitor CSS that is commonly used to program this function.

#### **MOSFET Gate Drive**

P-channel drive is derived through an internal regulator that generates VIN-5V. This pin (VDR) has to be connected to VIN with a 0.1uF decoupling capacitor. The gate drive circuit swings between VIN and VIN-5 and employs powerful drivers for efficient switching of the P-channel MOSFET.



#### **Power MOSFET Selection**

Select the Power MOSFET for Voltage rating  $BV_{DSS}$ , On resistance  $R_{DS(ON)}$ , and thermal resistance Rthja. BV<sub>DSS</sub> should be about twice as high as VIN in order to guard against switching transients. Recommended MOSFET voltage rating for VIN of 5V, 12V and 24V is 12V, 30V and 40V respectively. R<sub>DS(ON)</sub> has to be selected such that when operating at peak and junction temperature current Overcurrent threshold of the SP6126 is not exceeded. Allowing 50% for temperature coefficient of  $R_{\text{DS(ON)}}$  and 15% for inductor current ripple, the following expression can be used:

$$RDS(ON) \le \left(\frac{300mV}{1.5 \times 1.15 \times Iout}\right)$$

Within this constraint, selecting MOSFETs with lower  $R_{DS(ON)}$  will reduce conduction losses at the expense of increased switching losses. As a rule of thumb select the highest  $R_{DS(ON)}$  MOSFET that meets the above criteria. Switching losses can be assumed to roughly equal the conduction losses. A simplified expression for conduction losses is given by:

$$Pcond = Iout \times RDS(ON) \times \left(\frac{Vout}{Vin}\right)$$

MOSFET's junction temperature can be estimated from:

$$T = (2 \times Pc \times Rthja) + Tambient$$

#### **Schottky Rectifier selection**

Select the Schottky for Voltage rating  $V_R$ , Forward voltage  $V_f$ , and thermal resistance Rthja. Voltage rating should be selected using the same guidelines outlined for MOSFET voltage selection. For a low duty cycle application such as the circuit shown on first page, the Schottky is conducting most of the time and its conduction losses are the largest component of losses in the converter. Conduction losses can be estimated from:

$$Pc = Vf \times Iout \times \left(1 - \frac{Vout}{Vin}\right)$$

where:

Vf is diode forward voltage at IOUT

Schottky's AC losses due to its switching capacitance are negligible.

#### **Inductor Selection**

Select the Inductor for inductance L and saturation current ISAT. Select an inductor with ISAT higher than the programmed overcurrent. Calculate inductance from:

$$L = (Vin - Vout) \times \left(\frac{Vout}{Vin}\right) \times \left(\frac{1}{f}\right) \times \left(\frac{1}{Irip}\right)$$

where:

VIN is converter input voltage VOUT is converter output voltage f is switching frequency IRIP is inductor peak-to-peak current ripple (nominally set to 30% of IOUT)

Keep in mind that a higher IRIP results in a smaller inductor which has the advantages of small size, low DC equivalent resistance DCR, high saturation current ISAT and allows the use of a lower output capacitance to meet a given step load transient. A higher IRIP, however, increases the output voltage ripple and increases the current at which converter enters Discontinuous Conduction Mode. The output current at which converter enters DCM is ½ of IRIP. Note that a negative current step load that drives the converter into DCM will result in a large output voltage transient. Therefore the lowest current for a step load should be larger than ½ of IRIP.

#### **Output Capacitor Selection**

Select the output capacitor for voltage rating, capacitance and Equivalent Series Resistance (ESR). Nominally the voltage rating is selected to be twice as large as the output voltage. Select the capacitance to satisfy the specification for output voltage overshoot/undershoot caused by current step load. A steady-state output current IOUT corresponds to inductor stored energy of ½ L IOUT<sup>2</sup>.





A sudden decrease in IOUT forces the energy surplus in L to be absorbed by COUT. This causes an overshoot in output voltage that is corrected by power switch reduced duty cycle. Use the following equation to calculate COUT:

$$Cout = L \times \left(\frac{I_2^2 - I_1^2}{\text{Vos}^2 - \text{Vout}^2}\right)$$

Where:

L is the output inductance  $I_2$  is the step load high current  $I_1$  is the step load low current Vos is output voltage including overshoot Vout is steady state output voltage

Output voltage undershoot calculation is more complicated. Test results for SP6126 buck circuits show that undershoot is approximately equal to overshoot. Therefore above equation provides a satisfactory method for calculating COUT.

Select ESR such that output voltage ripple (VRIP) specification is met. There are two components to VRIP: First component arises from charge transferred to and from COUT during each cycle. The second component of VRIP is due to inductor ripple current flowing through output capacitor's ESR. It can be calculated from:

$$Vrip = Irip \times \sqrt{ESR^2 + \left(\frac{1}{8 \times Cout \times fs}\right)^2}$$

Where:

IRIP is inductor ripple current fs is switching frequency COUT is output capacitor calculated above

Note that a smaller inductor results in a higher IRIP, therefore requiring a larger COUT and/or lower ESR in order to meet VRIP.

#### **Input Capacitor Selection**

Select the input capacitor for Voltage, Capacitance, ripple current, ESR and ESL. Voltage rating is nominally selected to be twice the input voltage. The RMS value of input capacitor current, assuming a low inductor ripple current (IRIP), can be calculated from:

$$Icin = Iout \times \sqrt{D(1-D)}$$

In general total input voltage ripple should be kept below 1.5% of VIN (not to exceed 180mV). Input voltage ripple has three components: ESR and ESL cause a step voltage drop upon turn on of the MOSFET. During on time capacitor discharges linearly as it supplies IOUT-lin. The contribution to Input voltage ripple by each term can be calculated from:

$$\Delta V, Cin = \frac{Iout \times Vout \times (Vin - Vout)}{fs \times Cin \times Vin^2}$$

$$\Delta V$$
,  $ESR = ESR(Iout - 0.5Irip)$ 

$$\Delta V, ESL = ESL \frac{\left(Iout - 0.5Irip\right)}{Trise}$$

Where Trise is the rise time of current through capacitor

Total input voltage ripple is sum of the above:

$$\Delta V, Tot = \Delta V, Cin + \Delta V, ESR + \Delta V, ESL$$



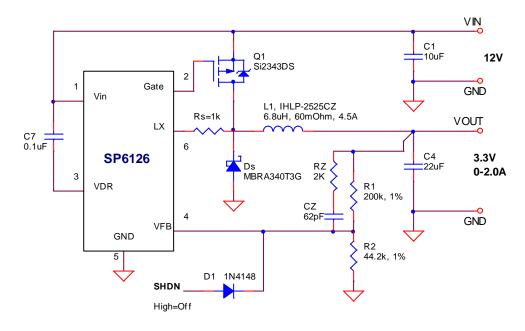


Figure 4- Application circuit for VIN=12V

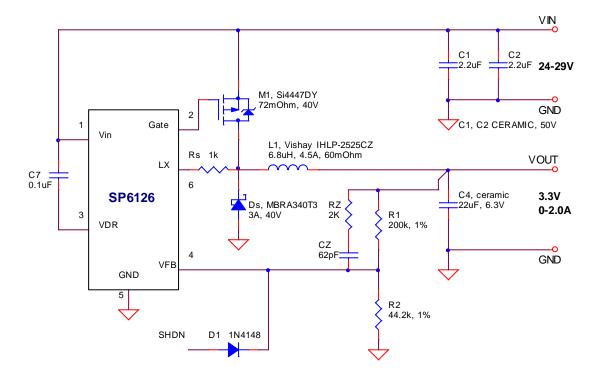


Figure 5- Application circuit for VIN = 24-29V



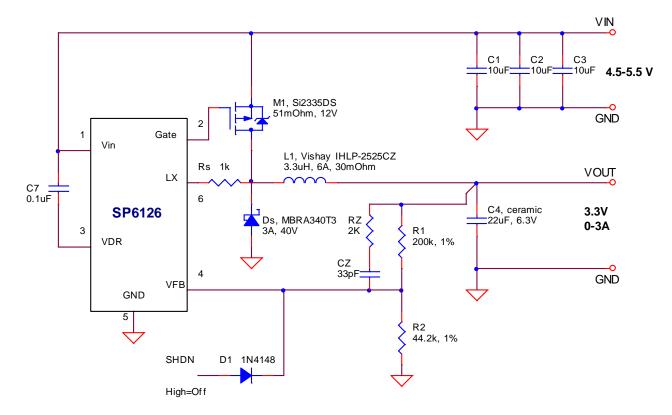


Figure 6- Application circuit for Vout = 4.5-5.5 V

#### TYPICAL PERFORMANCE CHARACTERISTICS

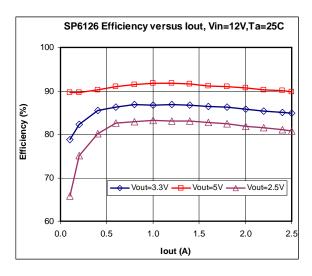


Figure 7- Efficiency at VIN = 12 ∨



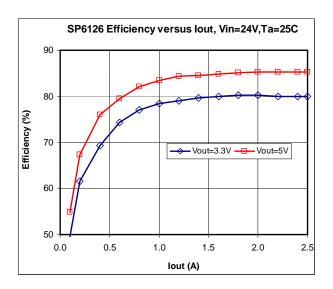


Figure 8- Efficiency at VIN = 24 V

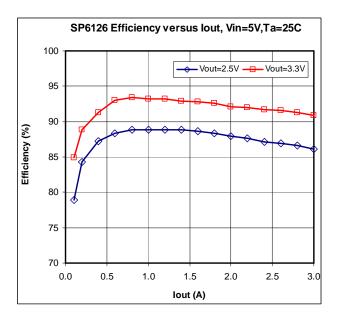


Figure 9- Efficiency at VIN = 5 V



#### TYPICAL PERFORMANCE CHARACTERISTICS

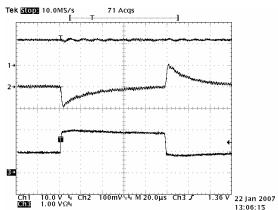


Figure 10- Step load 1-2A, ch1: Vin; ch2: Vout; ch3: lout

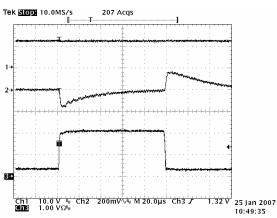


Figure 11- Step load 0.3-2A, ch1: Vin; ch2: Vout; ch3: lout

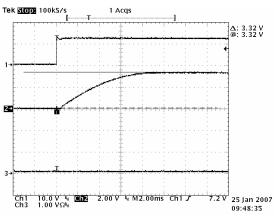


Figure 12- Startup no load, ch1: Vin ch2: Vout, ch3: lout

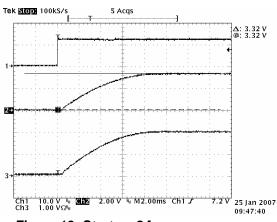


Figure 13- Start up 2A, ch1: Vin; ch2: Vout; ch3: Iout

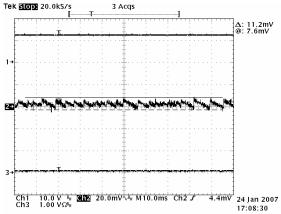


Figure 14- Output ripple at 0A is 11mV, ch1: VIN; ch2: VOUT; ch3: IOUT

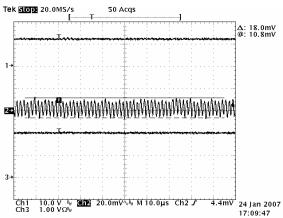
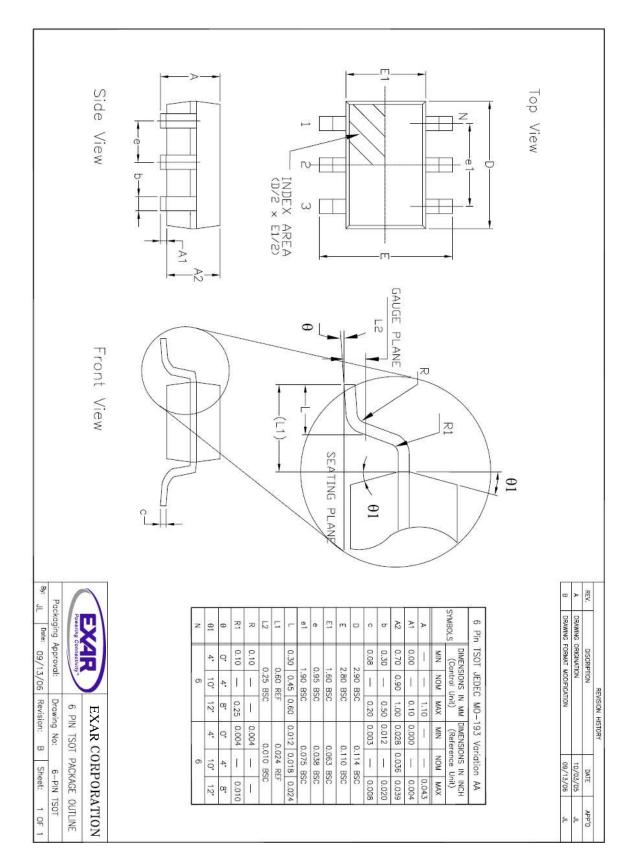


Figure 15- Output ripple at 2A is 18mV, ch1: VIN; ch2: VOUT; ch3: IOUT









#### ORDERING INFORMATION

Part Number	Temperature Range	Package
SP6126EK1-L	(I	Lead Free) 6 Pin TSOT
SP6126EK1-L/TR	40°C to +125°C(	Lead Free) 6 Pin TSOT

/TR = Tape and Reel Pack Quantity for Tape and Reel is 2500

For further assistance:

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